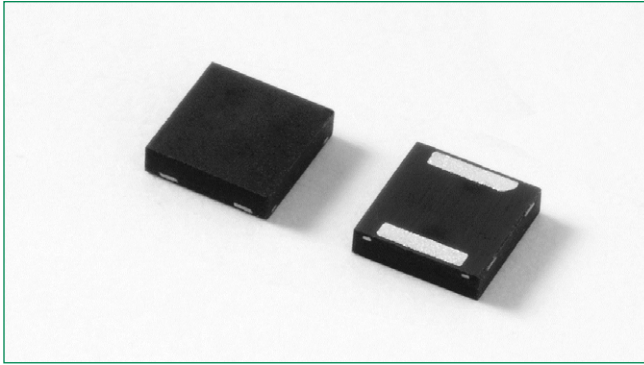


**Pxxx0Q22xLHL, Low IH Series – QFN 3.3X3.3**



**Description**

The Pxxx0Q22xLHL Low IH series is the low capacitance SIDACtor® component designed to protect high density broadband equipment from damaging overvoltage transients. It provides a low profile, chip scale surface mount solution that enables broadband equipment to comply with global regulatory standards while limiting the impact to broadband signals and board space.

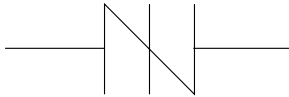
**Features and Benefits**

- Low profile
- Small footprint
- Low capacitance
- Low voltage overshoot
- Low on-state voltage
- Does not degrade surge capability after multiple surge events within limit.
- Fails short circuit when surged in excess of ratings
- Pb-free E3 means 2nd level interconnect is Pb-free and the terminal finish material is tin(Sn) (IPC/JEDEC J-STD-609A.01)
- Halogen-Free and RoHS-Compliant

**Agency Approvals**

Agency	Agency File Number
	E133083

**Schematic Symbol**



**Applicable Global Standards**

- TIA-968-A
- TIA-968-B
- ITU K.20/21 Enhanced Level
- ITU K.20/21 Basic Level
- GR 1089 Inter-building
- GR 1089 Intra-building
- IEC 61000-4-5 2nd Edition
- YD/T 1082
- YD/T 993
- YD/T 950

**Electrical Characteristics**

Part Number	Marking	$V_{DRM}$ @ $I_{DRM}=5\mu A$	$V_S$ @ 100V/ $\mu s$	$I_H$	$I_S$	$I_T$	$V_T$ @ $I_T=2.2$ Amps	Capacitance @ 1MHz, 2V bias	
		V min	V max	mA min	mA max	A max	V max	pF min	pF max
P4500Q22DLHL	P45DL	400	570	10	800	2.2	4	25	65

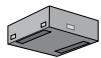
**Notes:**  
 - Absolute maximum ratings measured at  $T_A=25^\circ C$  (unless otherwise noted).  
 - Components are bi-directional (unless otherwise noted).

**Surge Ratings**

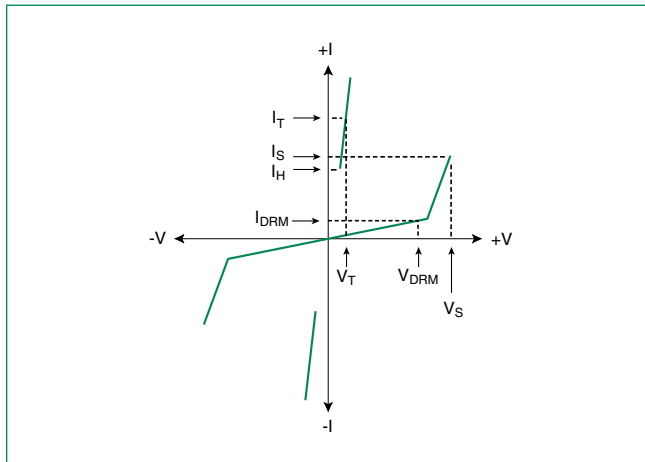
Series	$I_{PP}$								$I_{TSM}$ 50/60 Hz	di/dt
	0.2/310 <sup>1</sup> 0.5/700 <sup>2</sup>	2/10 <sup>1</sup> 2/10 <sup>2</sup>	8/20 <sup>1</sup> 1.2/50 <sup>2</sup>	10/160 <sup>1</sup> 10/160 <sup>2</sup>	5/320 <sup>1</sup> 9/720 <sup>2</sup>	10/360 <sup>1</sup> 10/360 <sup>2</sup>	10/1000 <sup>1</sup> 10/1000 <sup>2</sup>	5/310 <sup>1</sup> 10/700 <sup>2</sup>		
	A min	A min	A min	A min	A min	A min	A min	A typ		
D	-	600	550	-	-	-	130	250	50	500

**Notes:**  
 1. Current waveform in  $\mu s$   
 2. Voltage waveform in  $\mu s$   
 - Peak pulse current rating ( $I_{PP}$ ) is repetitive and guaranteed for the life of the product.  
 -  $I_{PP}$  ratings applicable over temperature range of  $-40^\circ C$  to  $+85^\circ C$   
 - The component must initially be in thermal equilibrium with  $-40^\circ C \leq T_J \leq +150^\circ C$

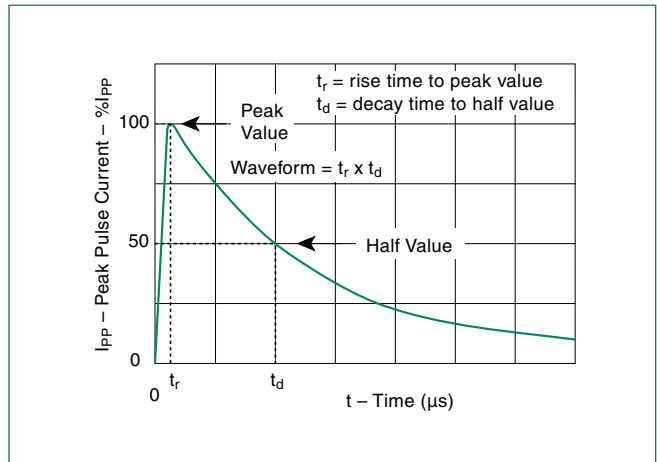
**Thermal Considerations**

Package	Symbol	Parameter	Value	Unit
3.3 x 3.3 QFN 	$T_J$	Operating Junction Temperature Range	-40 to +150	°C
	$T_S$	Storage Temperature Range	-65 to +150	°C
	$R_{\theta JA}$	Thermal Resistance: Junction to Ambient	120	°C/W

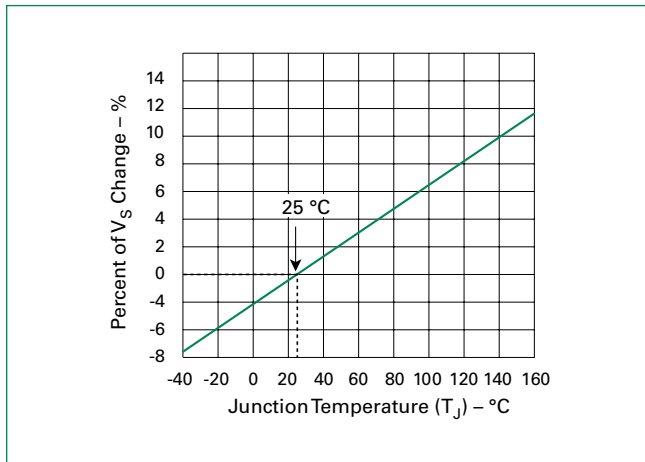
**V-I Characteristics**



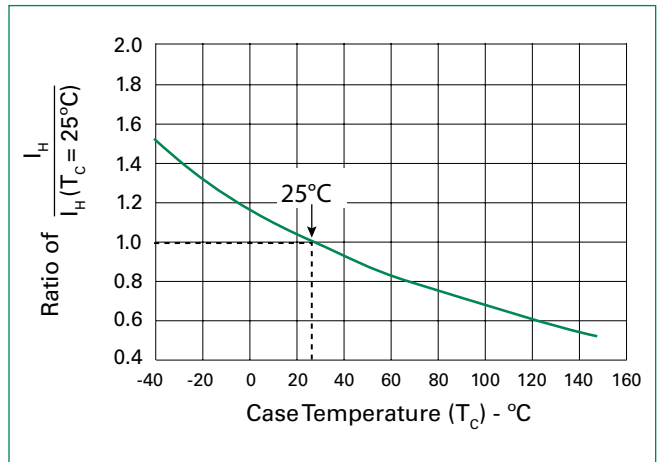
**$t_r \times t_d$  Pulse Waveform**



**Normalized  $V_S$  Change vs. Junction Temperature**

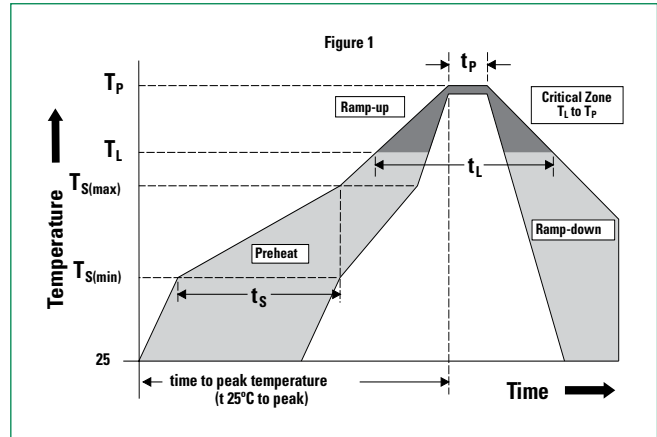


**Normalized DC Holding Current vs. Case Temperature**



### Soldering Parameters

<b>Reflow Condition</b>		Pb-Free assembly
<b>Pre Heat</b>	- Temperature Min ( $T_{s(min)}$ )	+150°C
	- Temperature Max ( $T_{s(max)}$ )	+200°C
	- Time (Min to Max) ( $t_s$ )	60-180 secs.
<b>Average ramp up rate (Liquidus Temp (<math>T_L</math>) to peak)</b>		3°C/sec. Max.
<b><math>T_{s(max)}</math> to <math>T_L</math> - Ramp-up Rate</b>		3°C/sec. Max.
<b>Reflow</b>	- Temperature ( $T_L$ ) (Liquidus)	+217°C
	- Temperature ( $t_l$ )	60-150 secs.
<b>Peak Temp (<math>T_p</math>)</b>		+260(+0/-5)°C
<b>Time within 5°C of actual Peak Temp (<math>t_p</math>)</b>		30 secs. Max.
<b>Ramp-down Rate</b>		6°C/sec. Max.
<b>Time 25°C to Peak Temp (<math>T_p</math>)</b>		8 min. Max.
<b>Do not exceed</b>		+260°C



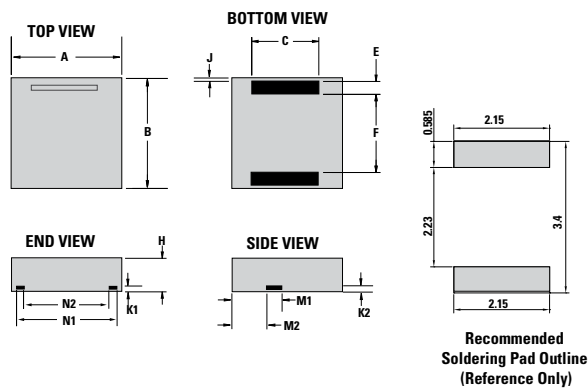
### Physical Specifications

<b>Lead Material</b>	Copper Alloy
<b>Terminal Finish</b>	100% Matte-Tin Plated
<b>Body Material</b>	UL Recognized compound meeting flammability rating V-0

### Environmental Specifications

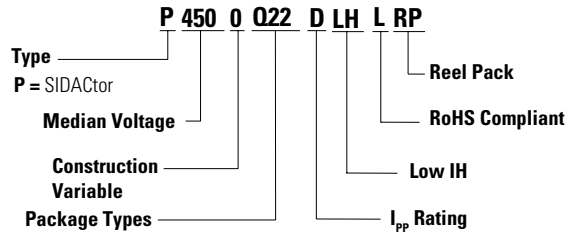
<b>High Temp Voltage Blocking</b>	80% Rated $V_{DRM}$ ( $V_{AC}$ Peak) +125°C or +150°C, 504 or 1008 hrs. MIL-STD-750 (Method 1040) JEDEC, JESD22-A-101
<b>Temp Cycling</b>	-65°C to +150°C, 15 min. dwell, 10 up to 100 cycles. MIL-STD-750 (Method 1051) EIA/JEDEC, JESD22-A104
<b>Biased Temp &amp; Humidity</b>	52 $V_{DC}$ (+85°C) 85%RH, 504 up to 1008 hrs. EIA/JEDEC, JESD22-A-101
<b>High Temp Storage</b>	+150°C 1008 hrs. MIL-STD-750 (Method 1031) JEDEC, JESD22-A-101
<b>Low Temp Storage</b>	-65°C, 1008 hrs.
<b>Thermal Shock</b>	0°C to +100°C, 5 min. dwell, 10 sec. transfer, 10 cycles. MIL-STD-750 (Method 1056) JEDEC, JESD22-A-106
<b>Resistance to Solder Heat</b>	+260°C, 30 secs. MIL-STD-750 (Method 2031)
<b>Moisture Sensitivity Level</b>	85%RH, +85°C, 168 hrs., 3 reflow cycles (+260°C Peak). JEDEC-J-STD-020, Level 1

### Dimensions — 3.3x3.3 QFN

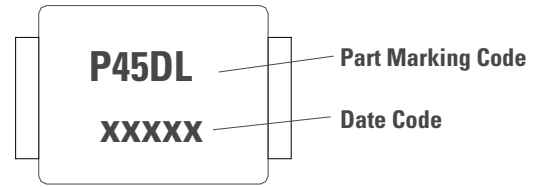


Dimensions	Inches		Millimeters	
	Min	Max	Min	Max
<b>A</b>	0.126	0.134	3.200	3.400
<b>B</b>	0.126	0.134	3.200	3.400
<b>C</b>	0.075	0.083	1.900	2.100
<b>E</b>	0.011	0.019	0.285	0.485
<b>F</b>	0.088	0.096	2.230	2.430
<b>H</b>	0.035	0.043	0.900	1.100
<b>J</b>	0.000	0.008	0.000	0.200
<b>K1</b>	0.004	0.012	0.100	0.300
<b>K2</b>	0.004	0.012	0.100	0.300
<b>M1</b>	0.063	0.071	1.610	1.810
<b>M2</b>	0.045	0.053	1.153	1.353
<b>N1</b>	0.095	0.103	2.420	2.620
<b>N2</b>	0.082	0.090	2.080	2.280

**Part Numbering**



**Part Marking**

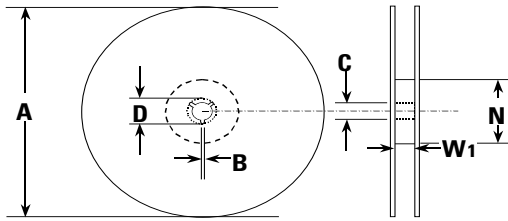


**Packing Options**

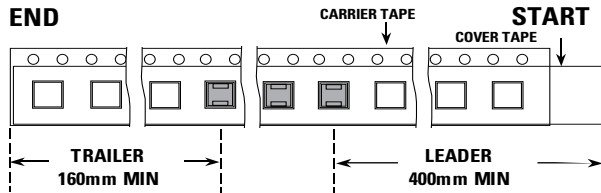
Package Type	Description	Quantity	Added Suffix	Industry Standard
Q22	3.3x3.3 QFN Tape and Reel Pack	5000	RP	EIA-481-D

**Tape and Reel Specifications — 3.3x3.3 QFN**

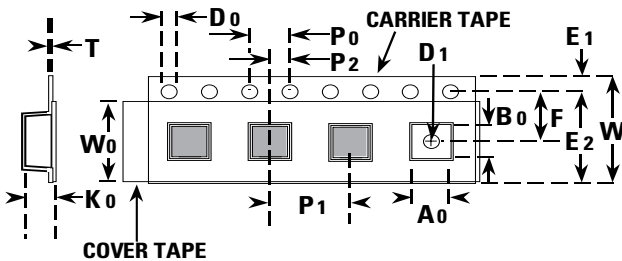
**Reel Dimension**



**Tape Leader and Trailer Dimensions**



**Tape Dimension Items**



Symbols	Description	Inches		Millimeters	
		Min	Max	Min	Max
A	Reel Diameter	N/A	12.992	N/A	330.0
B	Drive Spoke Width	0.059	N/A	1.50	N/A
C	Arbor Hole Diameter	0.504	0.531	12.80	13.50
D	Drive Spoke Diameter	0.795	N/A	20.20	N/A
N	Hub Diameter	1.969	N/A	50.00	N/A
W <sub>1</sub>	Reel Inner Width at Hub	0.488	0.567	12.40	14.40
A <sub>0</sub>	Pocket Width at Bottom	0.138	0.146	3.50	3.70
B <sub>0</sub>	Pocket Length at Bottom	0.138	0.146	3.50	3.70
D <sub>0</sub>	Feed Hole Diameter	0.059	0.063	1.50	1.60
D <sub>1</sub>	Pocket Hole Diameter	0.059	N/A	1.50	N/A
E <sub>1</sub>	Feed Hole Position 1	0.065	0.073	1.65	1.85
E <sub>2</sub>	Feed Hole Position 2	0.400	0.408	10.15	10.35
F	Feed Hole Center - Pocket Hole Center 2	0.215	0.219	5.45	5.55
K <sub>0</sub>	Pocket Depth	0.039	0.051	1.00	1.30
P <sub>0</sub>	Feed Hole Pitch	0.153	0.161	3.90	4.10
P <sub>1</sub>	Component Spacing	0.311	0.319	7.90	8.10
P <sub>2</sub>	Feed Hole Center - Pocket Hole Center 1	0.077	0.081	1.90	2.05
T	Carrier Tape Thickness	0.010	0.014	0.25	0.35
W	Embossed Carrier Tape Width	0.453	0.484	11.50	12.30
W <sub>0</sub>	Cover Tape Width	0.358	0.366	9.10	9.30